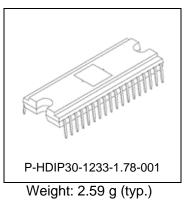
Intelligent Power Device

TPD4164K

High Voltage Monolithic Silicon Power IC

1. Description

The TPD4164K is a DC brush less motor driver using high voltage PWM control. It is fabricated by high voltage SOI process. It is three-shunt resistor circuit for current sensing. It contains level shift high-side driver, low-side driver, IGBT outputs, FRDs and protective functions for overcurrent circuit and under voltage protection circuits and thermal shutdown circuit. It is easy to control a DC brush less motor by just putting logic inputs from a MCU or motor controller to the TPD4164K.



2. Applications

DC brushless motor driver IC

3. Features

- High voltage power side and low voltage signal side terminal are separated.
- It is the best for current sensing in three shunt resistance.
- Bootstrap circuit gives simple high-side supply.
- Bootstrap diodes are built in.
- A dead time can be set as a minimum of 1 µs, and it is suitable for a Sine-wave from drive.
- 3-phase bridge output using IGBTs.
- Included over-current and under-voltage protection, shutdown function controlled by SD pin, and thermal shutdown.
- The regulator of 5 V (typ.) is built in.
- The package is a DIP type with 30 pin.

4. Block Diagram

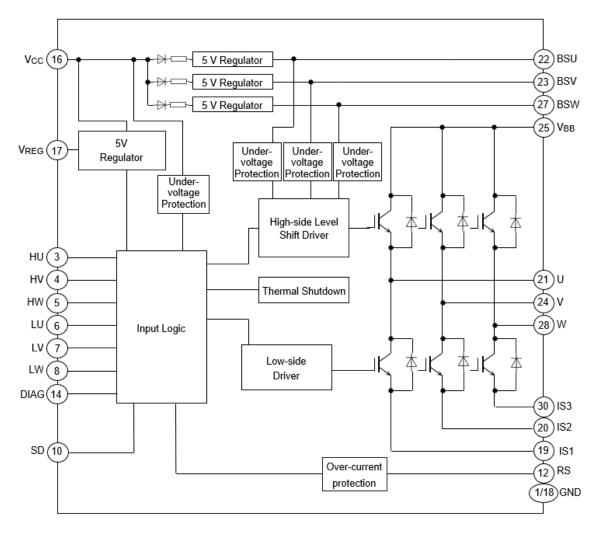


Figure 4.1 Block Diagram

5. Pin Assignments

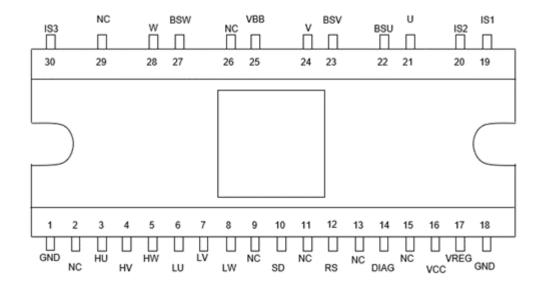
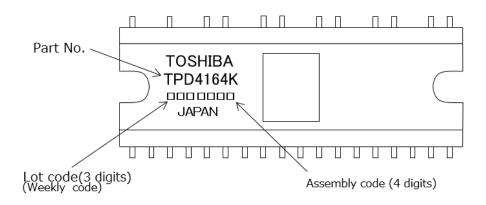


Figure 5.1 Pin Assignments

Marking



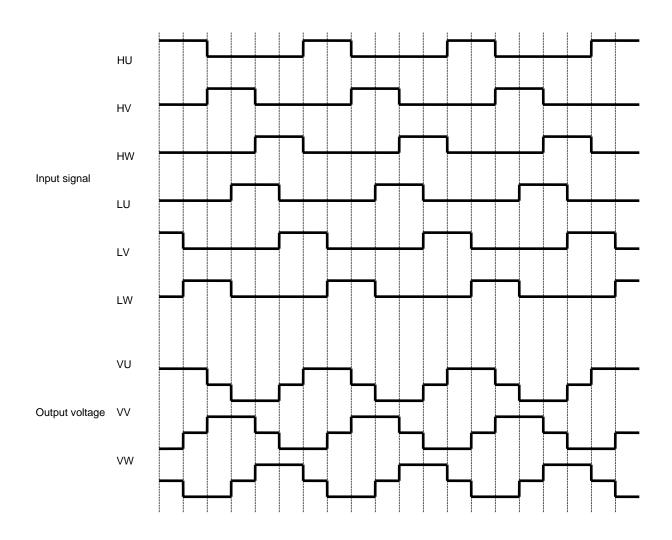
6. Pin Description

Pin No.	Symbol	Pin Description						
1	GND	Ground pin.						
2	NC	Unused pin, which is not connected to the chip internally.						
3	HU	The control terminal of IGBT by the high side of U. It turns off less than 1.5 V. It turns on more than 2.5 V.						
4	HV	The control terminal of IGBT by the high side of V. It turns off less than 1.5 V. It turns on more than 2.5 V.						
5	HW	The control terminal of IGBT by the high side of W. It turns off less than 1.5 V. It turns on more than 2.5 V.						
6	LU	The control terminal of IGBT by the low side of U. It turns off less than 1.5 V. It turns on more than 2.5 V.						
7	LV	The control terminal of IGBT by the low side of V. It turns off less than 1.5 V. It turns on more than 2.5 V.						
8	LW	The control terminal of IGBT by the low side of W. It turns off less than 1.5 V. It turns on more than 2.5 V.						
9	NC	Unused pin, which is not connected to the chip internally.						
10	SD	Input pin of external protection. ("L" active, It doesn't have hysteresis.)						
11	NC	Unused pin, which is not connected to the chip internally.						
12	RS	Over current detection pin.						
13	NC	Unused pin, which is not connected to the chip internally.						
14	DIAG	With the diagnostic output terminal of open drain, a pull-up is carried out by resistance. It turns on at the time of unusual.						
15	NC	Unused pin, which is not connected to the chip internally.						
16	Vcc	Control power supply pin. (15 V typ.)						
17	V _{REG}	5 V regulator output pin.						
18	GND	Ground pin.						
19	IS1	U-phase IGBT emitter and FRD anode pin.						
20	IS2	V-phase IGBT emitter and FRD anode pin.						
21	U	U-phase output pin.						
22	BSU	U-phase bootstrap capacitor connecting pin.						
23	BSV	V-phase bootstrap capacitor connecting pin.						
24	V	V-phase output pin.						
25	V _{BB}	High-voltage power supply input pin.						
26	NC	Unused pin, which is not connected to the chip internally.						
27	BSW	W-phase bootstrap capacitor connecting pin.						
28	W	W-phase output pin.						
29	NC	Unused pin, which is not connected to the chip internally.						
30	IS3	W-phase IGBT emitter and FRD anode pin.						

Table 6.1 Pin Description

7. Functional Description

7.1.1. Timing Chart





7.1.2. Truth Table

Table 7.1.2 Truth Table

	Input				High side		Low side							
Mode	HU	ΗV	HW	LU	LV	LW	SD	U phase	V phase	W phase	U phase	V phase	W phase	DIAG
Normal	Н	L	L	L	Н	L	Н	ON	OFF	OFF	OFF	ON	OFF	OFF
	Н	L	L	L	L	Н	Н	ON	OFF	OFF	OFF	OFF	ON	OFF
	L	Н	L	L	L	Н	Н	OFF	ON	OFF	OFF	OFF	ON	OFF
	L	Н	L	Н	L	L	Н	OFF	ON	OFF	ON	OFF	OFF	OFF
	L	L	Н	Н	L	L	Н	OFF	OFF	ON	ON	OFF	OFF	OFF
	L	L	Н	L	Н	L	н	OFF	OFF	ON	OFF	ON	OFF	OFF
Over-	Н	L	L	L	Н	L	H	OFF	OFF	OFF	OFF	OFF	OFF	ON
current	Н	L	L	L	L	Н	H	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	н	L	L	L	Н	H	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	н	L	Н	L	L	н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	L	Н	Н	L	L	H	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	L	Н	L	Н	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
Thermal	Н	L	L	L	Н	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
shutdown	Н	L	L	L	L	Н	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	Н	L	L	L	Н	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	Н	L	Н	L	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	L	Н	Н	L	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	L	Н	L	Н	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
Vcc Under-	Н	L	L	L	Н	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
voltage	Н	L	L	L	L	Н	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	Н	L	L	L	Н	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	Н	L	Н	L	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	L	Н	Н	L	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
	L	L	Н	L	Н	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	ON
VBS Under-	Н	L	L	L	Н	L	Н	OFF	OFF	OFF	OFF	ON	OFF	OFF
voltage	Н	L	L	L	L	Н	Н	OFF	OFF	OFF	OFF	OFF	ON	OFF
	L	Н	L	L	L	Н	Н	OFF	OFF	OFF	OFF	OFF	ON	OFF
	L	Н	L	Н	L	L	Н	OFF	OFF	OFF	ON	OFF	OFF	OFF
	L	L	Н	Н	L	L	Н	OFF	OFF	OFF	ON	OFF	OFF	OFF
	L	L	Н	L	Н	L	Н	OFF	OFF	OFF	OFF	ON	OFF	OFF
Irregular	Н	L	L	Н	L	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	OFF
(Note)	L	Н	L	L	Н	L	Н	OFF	OFF	OFF	OFF	OFF	OFF	OFF
	L	L	Н	L	L	Н	Н	OFF	OFF	OFF	OFF	OFF	OFF	OFF
SD	Х	Х	Х	Х	Х	Х	L	OFF	OFF	OFF	OFF	OFF	OFF	ON

X: Don't care

Note: Each phases of U, V and W turns OFF when the control signals of both high side and low side are "H" at the same time. (HU = "H" and LU = "H", HV = "H" and LV = "H", or HW = "H" and LW = "H")

7.2. Handling precautions

- (1) Please control the input signal in the state to which the V_{CC} voltage is steady. Both of the order of the V_{BB} power supply and the V_{CC} power supply are not cared about either. Note that if the power supply is switched off as described above, this product may be destroyed if the current regeneration route to the V_{BB} power supply is blocked when the V_{BB} line is disconnected by a relay or similar while the motor is still running.
- (2) Over voltage caused by a surge voltage over the absolute maximum ratings may destroy the circuit. Accordingly, be careful of handling the IC or of surge voltage in its application environment.

7.3. Description of Protection Function

(1) Under voltage protection

This product incorporates under voltage protection circuits to prevent the IGBT from operating in unsaturated mode when the VCC voltage or the VBS voltage drops.

When the VCC power supply falls to this product internal setting VCCUVD (=11 V typ.), all IGBT outputs shut down regardless of the input. This protection function has hysteresis. When the VCC power supply reaches 0.5 V higher than the shutdown voltage (VCCUVR (=11.5 V typ.)), this product is automatically restored and the IGBT is turned on again by the input. DIAG output is reversed at the time of VCC under-voltage protection. When the VCC power supply is less than 7 V, DIAG output isn't sometimes reversed. When the VBS supply voltage drops VBSUVD (=3 V typ.), the high-side IGBT output shuts down. When the VBS supply voltage reaches 0.5 V higher than the shutdown voltage (VBSUVR (=3.5V typ.)), the IGBT is turned on again by the input signal.

(2) Over-current protection

This product incorporates a over-current protection circuit to protect itself against over-current at startup or when a motor is locked. This protection function detects voltage generated in the current detection resistor connected to the RS pin. When this voltage exceeds V_R (=0.5 V typ.), the IGBT output, which is on, temporarily shuts down after a delay time, preventing any additional current from flowing to this product. The next all "L" signal releases the shutdown state.

(3) Thermal shutdown

This product incorporates a thermal shutdown circuit to protect itself against the abnormal state when its temperature rises excessively.

When the temperature of this chip rises to the internal setting TSD due to external causes or internal heat generation, all IGBT outputs shut down regardless of the input. This protection function has hysteresis Δ TSD (= 50°C typ.). When the chip temperature falls to TSD – Δ TSD, the chip is automatically restored and the IGBT is turned on again by the input.

Because the chip contains just one temperature detection location, when the chip heats up due to the IGBT, for example, the differences in distance from the detection location in the IGBT (the source of the heat) cause differences in the time taken for shutdown to occur. Therefore, the temperature of the chip may rise higher than the thermal shutdown temperature when the circuit started to operate.

(4) SD function

SD pin is the input signal pin to shut down the internal output IGBT. Output of all IGBT is shut down after delay times (2 µs (typ.)) when "L" signal is input to the SD pin from external circuit (MCU etc.). It is possible to shut down IC when overcurrent and others is detected by external circuit. Shut down state is released by all of IC input signal "L". At open state of SD pin, shut down function can not operate.

8. Absolute Maximum Ratings

Characteristics	Symbol	Rating	Unit
Demananahu walta na	V _{BB}	600	V
Power supply voltage	Vcc	20	V
Output current (DC)	lout	2	А
Output current (pulse 1ms)	l _{outp}	3	А
Rootstrap pin voltago (Noto1)	VBSX	600	V
Bootstrap pin voltage (Note1)	VBSX-X	- 0.5 to 6	V
Input voltage (Note2)	Vin	- 0.5 to 6	V
VREG current	IREG	50	mA
DIAG voltage	Vdiag	20	V
DIAG current	I _{DIAG}	20	mA
SD pin voltage	VSD	- 0.5 to V _{REG} + 0.5	V
RS pin voltage	V _{RS}	- 0.5 to V _{REG} + 0.5	V
IS pin voltage (Note3)	VIS	± 0.7	V
Power dissipation (IGBT 1-phase (Tc = 25°C))	Pc(IGBT)	27	W
Power dissipation (FRD 1-phase (Tc = 25°C))	Pc(FRD)	9	W
Operating junction temperature	Tjopr	- 40 to 135	°C
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	- 55 to 150	°C

Table 8.1Absolute Maximum Ratings $(T_a = 25^{\circ}C \text{ unless otherwise specified})$

Note1: V_{BSX-X}: BSU-U, BSV-V, BSW-W

Note2: VIN: HU, HV, HW, LU, LV, LW

Note3: Except for the peak voltage occurred in switching outputs including within the delay time of over current protection.

The absolute maximum ratings of a semiconductor device are a set of specified parameter values, which must not be exceeded during operation, even for an instant.

If any of these rating would be exceeded during operation, the device electrical characteristics may be irreparably altered and the reliability and lifetime of the device can no longer be guaranteed. Moreover, these operations with exceeded ratings may cause break down, damage, and/or degradation to any other equipment. Applications using the device should be designed such that each maximum rating will never be exceeded in any operating conditions.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

9. Operating Ranges

Table 9.1	Operating Ranges(T _a = 25°C unless otherwise specified)

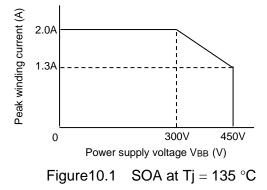
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Operating power supply veltage	V _{BB}	—	50	280	450	V	
Operating power supply voltage	Vcc	_	13.5	15	16.5	V	

10. Electrical Characteristics

Table 10.1 Electrical Characteristics(T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Current dissinction	IBB	V _{BB} = 450 V	—	—	0.5	mA	
Current dissipation	lcc	Vcc = 15 V	_	0.8	1.5		
Restation Current dissipation	IBS (ON)	$V_{BS} = 5 V$, high side ON	—	90	150		
Bootstrap Current dissipation	IBS (OFF)	$V_{BS} = 5 V$, high side OFF	_	80	140	μA	
Input voltage	VIH	VIN = "H", VCC = 15 V	2.5	_	—	v	
input voitage	VIL	VIN = "L" , VCC = 15 V	_	_	1.5		
Input ourront	lih	VIN = 5 V	_	_	50		
Input current	١L	VIN = 0 V	_	_	10	μA	
	V _{CEsat} H	V _{CC} = 15 V, I _C = 1 A, high side	_	3.0	3.7	V	
Output saturation voltage	VCEsatL	V _{CC} = 15 V, I _C = 1 A, low side	_	3.0	3.7	v	
EPD forward voltage	VFH	IF = 1 A, high side	_	2.5	3.2	V	
FRD forward voltage	VFL	IF = 1 A, low side	_	2.5	3.2		
Regulator voltage	Vreg	V _{CC} = 15 V, I _{REG} = 30 mA	4.5	5	5.5	V	
Over current protection voltage	VR	_	0.46	0.5	0.54	V	
Over current protection delay time	Dt	_	_	2	3	μs	
Thermal shutdown temperature	TSD	V _{CC} = 15 V	135	_	165	°C	
Thermal shutdown hysteresis	ΔTSD	Vcc = 15 V	_	50	—	°C	
VCC under voltage protection VCCUVD		_	10	11	12	V	
V _{CC} under voltage protection recovery	V _{CC} UVR	_	10.5	11.5	12.5	V	
V _{BS} under voltage protection	V _{BS} UVD	_	2	3	4	V	
V _{BS} under voltage protection recovery	V _{BS} UVR	_	2.5	3.5	4.5	V	
DIAG saturation voltage	VDIAGsat	IDIAG = 5 mA	_	_	0.5	V	
Minimum operating pulse width	PWmin	V _{BB} = 280 V, V _{CC} = 15 V	0.8	_	_	μs	
SD Input voltage V _{SD}		V _{CC} =15V	—	2.5	_	V	
Output on delay time	t _{on}	V _{BB} = 280 V, V _{CC} = 15 V, I _C = 1 A	—	1.0	1.5	μs	
Output off delay time	toff	V _{BB} = 280 V, V _{CC} = 15 V, I _C = 1 A	_	1.2	1.7	μs	
Dead time	tdead	V _{BB} = 280 V, V _{CC} = 15 V, I _C = 1 A	1	_	_	μs	
FRD reverse recovery time	t _{rr}	$V_{BB} = 280 \text{ V}, \text{ V}_{CC} = 15 \text{ V}, \text{ I}_{C} = 1 \text{ A}$	—	200	_	ns	

Safe Operating Area



11. Application Circuit Example

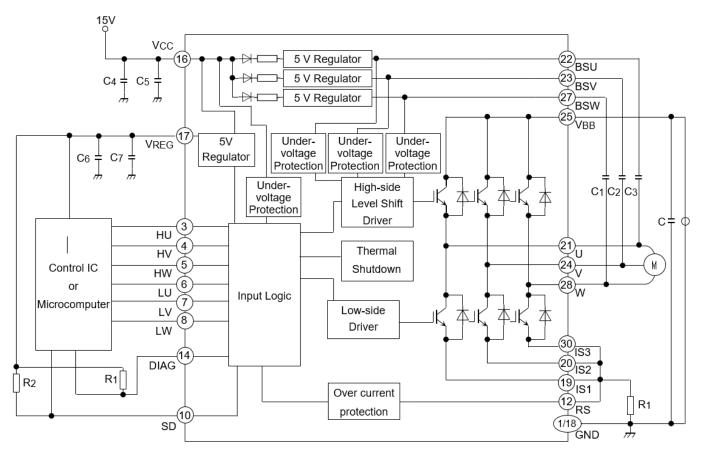


Figure 11.1 Application Circuit Example

Typical external parts are shown in the following table.

Part	Typical	Purpose	Remarks	
C ₁ , C ₂ , C ₃	25 V/2.2 μF	Bootstrap capacitor	(Note 1)	
C ₄	25 V/10 μF	V _{CC} power supply stability	(Note 2)	
C ₅	25 V/0.1 μF	V _{CC} for surge absorber	(Note 2)	
C ₆	25 V/10 μF	VREG power supply stability	(Note 2)	
C ₇	25 V/0.1 μF	V _{REG} for surge absorber	(Note 2)	
R ₁	5.1 kΩ	DIAG pin pull-up resistor	(Note 3)	
R ₂	10 kΩ	SD pin pull-up resistor	-	
R ₃	0.35 $\Omega\pm$ 1 % (1 W)	Over current detection	(Note 4)	

 Table 11.1
 Typical external parts

Note 1: The required bootstrap capacitance value varies according to the motor drive conditions. The capacitor is biased by 5V(typ.) and must be sufficiently derated for it.

Note 2: When using this product, adjustment is required in accordance with the use environment. When mounting, place as close to the base of this product leads as possible to improve the ripple and noise elimination.

Note 3: The DIAG pin is open drain. If not using the DIAG pin, connect to the GND.

Note 4: The following formula shows the detection current: $IO = VR / R_3$ (For VR = 0.5 V typ.)

12. Package Information

12.1. Package Dimensions

P-HDIP30-1233-1.78-001

Unit: mm

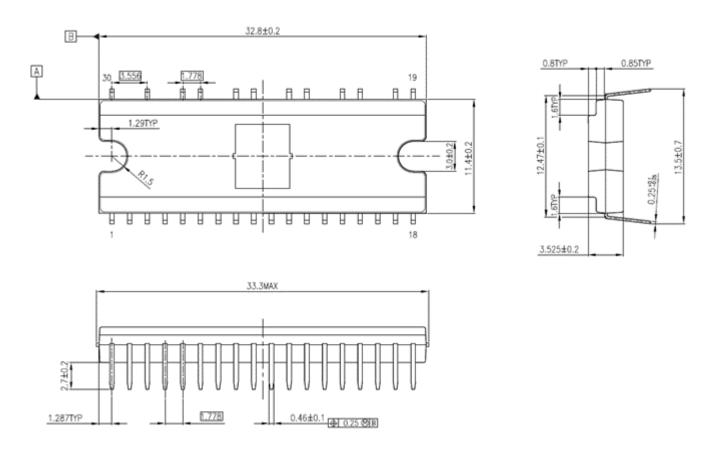


Figure 12.1 Package Dimensions

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